


## APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

<b>Title of Invention</b>	[HEAT SINK FOR CHIP PACKAGE AND BONDING METHOD THEREOF]		
Application Type : regular, utility Attorney Docket Number : 10233-US-PA			
Correspondence address: Customer Number: 31561 			
Priority Data: Doc.No: 91137108; Country -TW ; Date: 2002-12-24 us-priority-claimed			
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